



**Please note that Cypress is an Infineon Technologies Company.**

The document following this cover page is marked as “Cypress” document as this is the company that originally developed the product. Please note that Infineon will continue to offer the product to new and existing customers as part of the Infineon product portfolio.

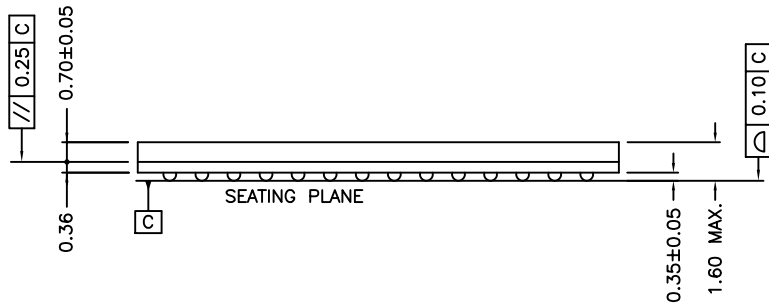
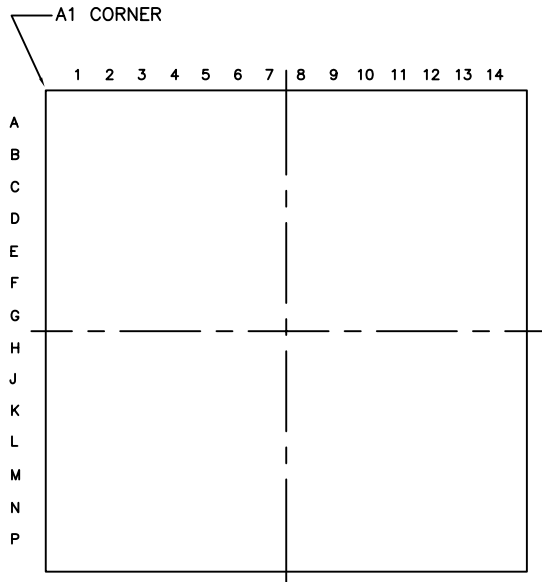
**Continuity of document content**

The fact that Infineon offers the following product as part of the Infineon product portfolio does not lead to any changes to this document. Future revisions will occur when appropriate, and any changes will be set out on the document history page.

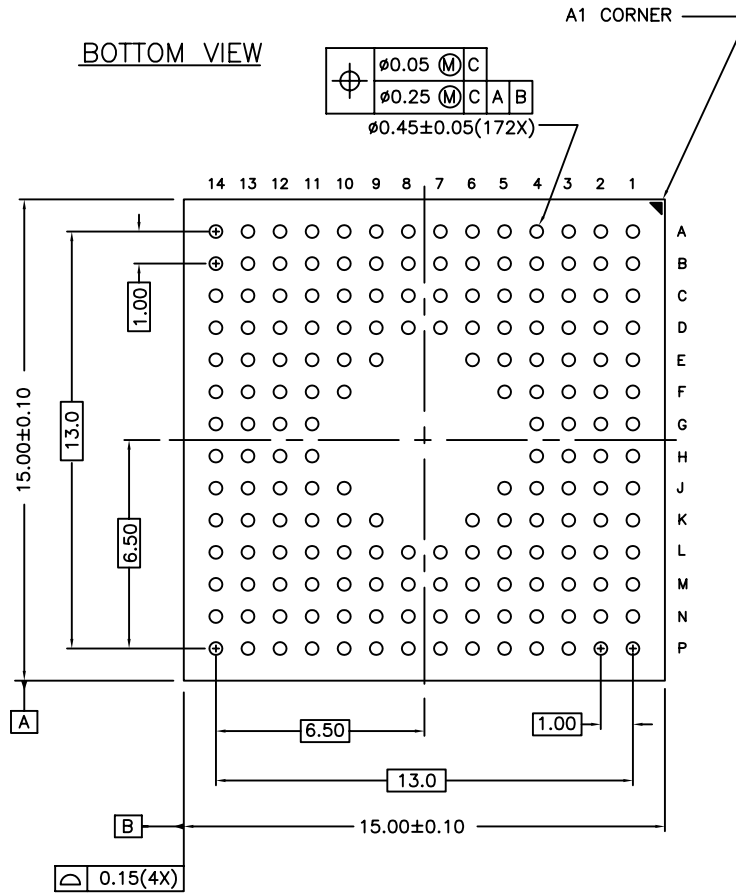
**Continuity of ordering part numbers**

Infineon continues to support existing part numbers. Please continue to use the ordering part numbers listed in the datasheet for ordering.

TOP VIEW



BOTTOM VIEW



PACKAGE WEIGHT - 0.6 grams  
 Jedec Publication 95, Design Guide 4.14


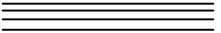
CYPRESS Company Confidential	
TITLE PACKAGE OUTLINE, 172L FBGA 15X15X1.6 MM BB172SD (FOR SINGLE OR STACKED DIE)	
SPEC NO. 51-85146	REV *E
SCALED TO FIT N/A	SHEET 1 OF 2

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PACKAGE CODE(S)

BBOAE  
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REV.	ECN NO.	ORIGIN OF CHANGE	DESCRIPTION OF CHANGE
**	109473	—	NEW RELEASE
*A	115632	—	ADD SUBSTRATE DIM./ ADD MOLD CAP DIM./ CHG. BALL HEIGHT DIM./ CHG. PKG. BODY TOLERANCE.
*B	397717	—	Change title and pkg thickness.
*C	2812922	—	Change Template and title from 172 FBGA (15x15x1.6mm) PKG. OUTL. FOR SINGLE or STACKED DIE to PACKAGE OUTLINE, 172L FBGA 15X15X1.6 MM BB172SD (FOR SINGLE OR STACKED DIE).
*D	3278135	—	No Change. Sunset Review.
*E	4600782	XANC	FOR SUNSET REVIEW. UPDATE DRAWING TEMPLATE.

 <b>CYPRESS</b>		
Company Confidential		
<b>TITLE</b> PACKAGE OUTLINE, 172L FBGA 15X15X1.6 MM BB172SD (FOR SINGLE OR STACKED DIE)		
<b>SPEC NO.</b> 51-85146	<b>REV</b> *E	
SCALED TO FIT	N/A	SHEET 2 OF 2

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